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RX12864D2-YHW

SPECIFICATION

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:



Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2014/11/14		First issue
Α	2016/02/25		Modify Precautions in
			use of LCD Modules
			& Static electricity
			test
В	2016/11/25		Add FPC bending
			rule



Contents

- 1. General Specification
- 2. Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing & Block Diagram
- 5. Optical Characteristics
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- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of LCD Modules
- 12. Material List of Components for RoHs
- 13. Recommendable Storage



1.General Specification

The Features of the Module is description as follow:

■ Module dimension: 90.0 x 52.8 x 6.6 mm

■ View area: 70.7 x 38.8 mm

Active area: 66.52 x 33.24 mm

■ Number of Dots: 128 x 64

■ Dot size: 0.48 x0.48 mm

■ Dot pitch: 0.52 x 0.52 mm

■ LCD type: STN Positive, Yellow Green Transflective

■ Duty: 1/64 , 1/9 Bias

View direction:6 o'clock

■ Backlight Type: LED White

■ IC: ST7565P



2. Module Classification Information

<u>R</u>	<u>X</u>	12864	<u>D2</u>	_	<u>Y</u>	<u>H</u>	W
①	2	3	4	_	(5)	6	7

Item	Description							
1	R : Raystar Optronics Inc.							
0	Dioploy	C : Character Type,		T:TAB Type				
2	Display	G: Graphic Type		X:COG Type				
3	Display Font :	128 * 64 dot						
4	Serials code:							
		P→TN Positive, Gray		V→FSTN Ne	egative, Blue			
		N→TN Negative,		T→FSTN Ne	egative, Black			
		L→VA Negative		D→FSTN No	egative (Double film)			
		H→ HTN Positive, Gray		F→FSTN Po	sitive			
5	LCD	I→HTN Negative, Black		K→FSC Neg				
		U→HTN Negative, Blue		S→FSC Pos				
		B→STN Negative, Blue			gative, Black			
		G→STN Positive, Gray		C→CSTN Negative, Black				
		Y→STN Positive, Yellow	Green	A→ASTN Negative, Black				
		A: Reflective, N.T, 6:00		K: Transflective, W.T,12:00				
	Polarizer	D: Reflective, N.T, 12:00		1 : Transflective, U.T,6:00				
	Type,	G: Reflective, W. T, 6:00		4 : Transflective, U.T.12:00				
	Temperature	J: Reflective, W. T, 12:0			C: Transmissive, N.T,6:00			
6	range,		0 : Reflective, U. T, 6:00		F: Transmissive, N.T,12:00			
		3 : Reflective, U. T, 12:0		I: Transmissive, W. T, 6:00				
	View	B: Transflective, N.T,6:0			ssive, W.T,12:00			
	direction	E: Transflective, N.T.12			ssive, U. T, 6:00			
		H: Transflective, W.T,6:00		5 : Transmissive, U.T,12:00				
	1	N→ Without backlight	W→LED	•	H→LED, High light White			
		P→EL, Blue	A→LED		S→LED, Full color			
		T→EL, Green	R→LED	•	J→DIP LED, Blue			
7	Backlight	D→EL, White), Orange	K→DIP LED, White			
		M→EL, Yellow Green	B→LED		E→DIP LED, Yellow			
		F→CCFL, White		, Dual color	L→DIP LED, Amber			
		Y→LED, Yellow Green	U→LED	, Full color	I→DIP LED, Red			
	7	G→LED, Green						



3.Interface Pin Function

Pin No.	Symbol	Level	Description
			This is the chip select signal. When /CS1 = "L", then the
1	/CS1		chip select becomes active, and data/command I/O is
			enabled.
2	/RES		When /RES is set to "L" , the settings are initialized.
			This is connect to the least significant bit of the normal
_			MPU address bus, and it determines whether the data
3	A0		bits are data or a command.
			A0 = "H": Indicates that D0 to D7 are display data.
			A0 = "L": Indicates that D0 to D7 are control data.
			When connected to an 8080 MPU, this is active LOW.
			(R/W) This terminal connects to the 8080 MPU /WR
			signal. The signals on the data bus are latched at the
4	/WR(R/W)		rising edge of the /WR signal.
	, ,		When connected to a 6800 Series MPU:
			This is the read/write control signal input terminal.
			When R/W = "H": Read.
			When R/W = "L": Write.
			When connected to an 8080 MPU, this is active LOW.
		\(\)	(E) This pin is connected to the /RD signal of the 8080
5	/DD/E)		MPU, and the ST7565P series data bus is in an output
5	/RD(E)		status when this signal is "L".
			When connected to a 6800 Series MPU, this is active HIGH.
	7		This is the 6800 Series MPU enable clock input terminal.
6	DB0		This is the 6000 Series wil o enable clock input terminal.
7	DB1		
8	DB2		
9	DB3		This is an 8-bit bi-directional data bus that connects to
10	DB4		an 8-bit or 16-bit standard MPU data
11	DB5		Bus.
12	DB6		
13	DB7		



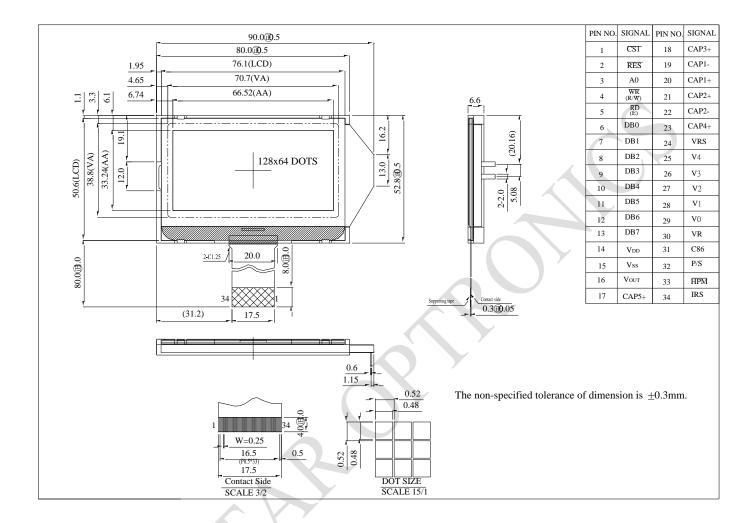
14	VDD	Shared with the MPU power supply terminal VDD. (3.3 V)					
15	VSS	This is a 0V terminal connected to the system GND.					
16	VOUT	DC/DC voltage converter. Connect a capacitor between this terminal and VSS.					
17	CAP5+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1- terminal.					
18	CAP3+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1- terminal.					
19	CAP1-	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1+ terminal.					
20	CAP1+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1- terminal.					
21	CAP2+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2- terminal.					
22	CAP2-	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2+ terminal.					
23	CAP4+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2- terminal.					
24	VRS	This is the externally-input VREG power supply for the LCD power supply voltage regulator.					
25	V4	This is a multi-level power supply for the liquid crystal					
26	V3	drive. The voltage Supply applied is determined by the					
27	V2	liquid crystal cell, and is changed through the use of a resistive voltage divided or through changing the					
28	V1	impedance using an op. amp. Voltage levels are determined based on Vss, and must					
29	VO	maintain the relative magnitudes shown below. $V0 \ge V1 \ge V2 \ge V3 \ge V4 \ge Vss$ When the power supply turns ON, the internal power supply circuits produce the V1 to V4 voltages shown below. The voltage settings are selected using the LCD bias set command.					
		V1 8/9*V0,6/7*V0 7/8*V0,5/6*V0 5/6*V0,4/5*V0 7/8*V0,5/6*V0 7/8*V0,5/6*V0 V2 7/9*V0,5/7*V0 6/8*V0,4/6*V0 4/6*V0,3/5*V0 6/8*V0,4/6*V0 6/8*V0,4/6*V0 V3 2/9*V0,2/7*V0 2/8*V0,2/6*V0 2/6*V0,2/5*V0 2/8*V0,2/6*V0 V4 1/9*V0,1/7*V0 1/8*V0,1/6*V0 1/6*V0,1/5*V0 1/8*V0,1/6*V0 1/8*V0,1/6*V0					



30	VR	Output voltage regulator terminal. Provides the voltage between VDD and V5 through a resistive voltage divider. IRS = "L": the V5 voltage regulator internal resistors are not used. IRS = "H": the V5 voltage regulator internal resistors are used.
31	C86	This is the MPU interface switch terminal. C86 = "H": 6800 Series MPU interface. C86 = "L": 8080 MPU interface.
32	P/S	This is the parallel data input/serial data input switch terminal. P/S = "H": Parallel data input. P/S = "L": Serial data input. The following applies depending on the P/S status: P/S Data/Command Data Read/Write Serial Clock H A0 D0 to D7 RD WR X L A0 SI (D7) Write only SCL (D6) When P/S = "L", D0 to D5 may be "H", "L" or Open. RD (E) and WR (R/W) are fixed to either "H" or "L". With serial data input, It is impossible read data from RAM.
33	/HPM	This is the power control terminal for the power supply circuit for liquid crystal drive. HPM = "H": Normal mode HPM = "L": High power mode
34	IRS	This terminal selects the resistors for the V5 voltage level adjustment. IRS = "H": Use the internal resistors IRS = "L": Do not use the internal resistors. The V5 voltage level is regulated by an external resistive voltage divider attached to the VR terminal



4.Contour Drawing



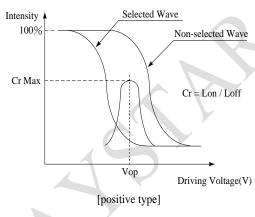


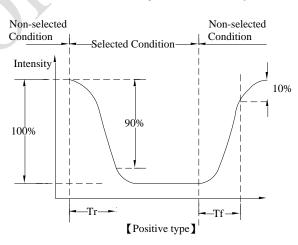
5.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR <u>≥</u> 2	0	_	20	ψ= 180°
View Angle	θ	CR <u>≥</u> 2	0	_	40	ψ= 0°
	θ	CR <u>≥</u> 2	0	_	30	ψ= 90°
	θ	CR <u>≥</u> 2	0	1	30	ψ= 270°
Contrast Ratio	CR	_		3	_	_
Poononce Time	T rise	- /	1	200	300	ms
Response Time	T fall		7	250	350	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)





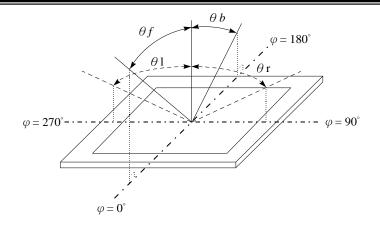
Conditions:

Operating Voltage : Vop Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≥2)







6.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	T _{ST}	-30	_	+80	ů
Power Supply Voltage	VDD	-0.3	_	3.6	V
Power supply voltage (VDD standard)	V0, VOUT	-0.3	4	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3		V0+0.3	V



7. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V _{DD} -V _{SS}	_	2.7	3.0	3.3	V
Supply Voltage For LCM	V ₀ -V _{SS}	Ta=-20°C Ta=25°C	10.0 9.8	10.2 10.0	10.4 10.2	< <
*NOTE		Ta=70°C	9.6	9.8	10.0	V
Input High Volt.	VIH	_	0.8 V _{DD}		V_{DD}	V
Input Low Volt.	VıL	-	Vss	_	0.2 V _{DD}	V
Output High Volt.	Vон		0.8 V _{DD}	_	V _{DD}	V
Output Low Volt.	Vol		Vss	_	0.2V _{DD}	V
Supply Current(No include LED Backlight)	loo	V _{DD} =3.0V	_	0.6	1	mA

NOTE: Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance



8.Backlight Information

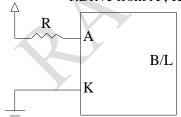
Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	14.4	16	25	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	-
Reverse Voltage	VR	_	_	5	v	-
Luminance	IV	75	95	_	CD/M ²	ILED=16mA
(Without LCD)		70			05/111	ille joina
LED Life Time					1	IĽED=16mA
(For Reference	_	_	50K		Hr.	25°C,50-60%RH,
only)						(Note 1)
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.







9. Reliability

	Environmental Test					
Test Item	Content of Test	Test Condition	Note			
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2			
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2			
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs				
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1			
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2			
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles				
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times				

Content of Reliability Test (Wide temperature, -20°C~70°C)

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



10.Inspection specification

NO	Item	Criterion				AQL	
		1.1 Missing vertical, horizontal segment, segment contrast					
		defect.					
		1.2 Missing char	1.2 Missing character, dot or icon.				
	Electrical	1.3 Display malfunction.					
01	Testing	1.4 No function	or no displ	ay.		0.65	
	resung	1.5 Current cons	sumption e	exceeds product sp	pecifications.		
		1.6 LCD viewing	angle def	fect.			
		1.7 Mixed produ	ct types.				
		1.8 Contrast def	ect.				
	Black or white	2.1 White and b	lack spots	on display \leq 0.25	mm, no more than		
02	spots on LCD	three white c	r black sp	ots present.	Y	2.5	
02	(display only)	2.2 Densely spa	ced: No more than two spots or lines within		s or lines within	2.0	
	3mm						
		3.1 Round type		ring drawing			
		Ф=(x + y) /	2	SIZE	Acceptable Q TY		
				Ф≦0.10	Accept no dense		
				0.10<Φ≦0.20	2		
				0.20<Φ≦0.25	1	2.5	
		1		0.25<Ф	0	2.0	
	LCD black	X	1				
	spots, white	→	<u>¥</u> .				
03	spots,	• •	x Y				
	contamination		Te e				
	(non-display)	3.2 Line type : (/	As followin	g drawing)			
		0.00	Length	Width	Acceptable Q TY		
1		~ / <u>* w</u>		W≦0.02	Accept no dense		
		→ i i i←	L≦3.0	0.02 <w≦0.03< td=""><td>2</td><td>2.5</td></w≦0.03<>	2	2.5	
	<i></i>	87E.0	L≦2.5	0.03 <w \u220e90.05<="" td=""><td>2</td><td></td></w>	2		
	-			0.05 < W	As round type		





04	Polarizer bubbles	specifications, not easy	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi < 1.00$	Acceptable Q TY Accept no dense	2.5
0.4	04 Polarizer specifications, not easy to find, must check in		0.20<Φ≦0.50	3	2.5
04				2	
		specify direction.	1.00<Ф	0	
			Total Q TY	3	





NO	Item	Criterion A			AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
			Glass thickness a: LCD	hickness side length	
		6.1 General glass chip 6.1.1 Chip on panel sur	face and crack between	panels:	
		z: Chip thickness	y: Chip width	x: Chip length	
06	Chipped	Z≦1/2t	Not over viewing area	x≦1/8a	2.5
	glass	1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more 6.1.2 Corner crack:	chips, x is total length of	of each chip.	
		z: Chip thickness	y: Chip width	x: Chip length	
8		Z≦1/2t	Not over viewing area	x≦1/8a	
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more	chips, x is the total leng	th of each chip.	



NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:	
		Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$	
06	Glass crack	6.2.2 Non-conductive portion:	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L$ $x \le 1/8a$ $0 < z \le t$	
0		 If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. 	
		y: width x: length	
		y. width x . length $y \le 1/3L$ $x \le a$	
		y	



YSTAR	I				
NO	Item	Criterion			
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5		
		8.1 Illumination source flickers when lit.	0.65		
08 Backlight elements		8.2 Spots or scratched that appear when lit must be judged.	2.5		
		Using LCD spot, lines and contamination standards.			
		8.3 Backlight doesn't light or color wrong.	0.65		
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5		
09	Bezel	stains or other contamination.	0.65		
		9.2 Bezel must comply with job specifications.	0.00		
		10.1 COB seal may not have pinholes larger than 0.2mm or			
		contamination.	2.5		
		10.2 COB seal surface may not have pinholes through to the			
		IC.	2.5		
		10.3 The height of the COB should not exceed the height	0.65		
		indicated in the assembly diagram.			
		10.4 There may not be more than 2mm of sealant outside the			
		seal area on the PCB. And there should be no more than three places.			
		10.5 No oxidation or contamination PCB terminals.			
10			2.5		
		characteristic chart. There should be no wrong parts,	0.65		
		missing parts or excess parts.			
		10.7 The jumper on the PCB should conform to the product			
		characteristic chart.	0.65		
	1	10.8 If solder gets on bezel tab pads, LED pad, zebra pad or			
		screw hold pad, make sure it is smoothed down.	2.5		
	X	10.9 The Scraping testing standard for Copper Coating of PCB			
			2.5		
Q		X			
		X * Y<=2mm2			
		11.1 No un-melted solder paste may be present on the PCB.	2.5		
	_	11.2 No cold solder joints, missing solder connections,	2.5		
11	Soldering	oxidation or icicle.			
		11.3 No residue or solder balls on PCB.	2.5		
		11.4 No short circuits in components on PCB.	0.65		



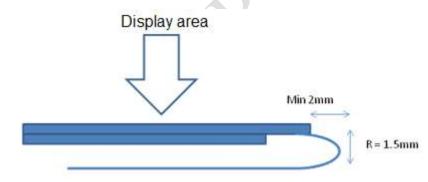


NO	Item	Criterion	AQL
NO 12	Item General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins.	2.5 0.65 2.5 2.5 2.5 0.65 0.65 0.65
	12.10 Product packaging must the same as specified or packaging specification sheet.	12.10 Product packaging must the same as specified on	0.65
		specification sheet. 12.12 Visual defect outside of VA is not considered to be rejection.	



11.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) The limitation of FPC bending





12.Material List of Components for RoHs

1. RAYSTAR Optronics. Inc. hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement: (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.



13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



Page: 1

		raye. I				
LCM Sample Estimate Feedback Sheet						
Module Number :						
1 · Panel Specification :						
1. Panel Type:	□ Pass	□ NG ,				
2. View Direction:	□ Pass	□ NG ,				
3. Numbers of Dots:	□ Pass	□ NG ,				
4. View Area:	□ Pass	□ NG ,				
5. Active Area:	□ Pass	□ NG ,				
6.Operating Temperature:	□ Pass	□ NG ,				
7.Storage Temperature :	□ Pass	□ NG ,				
8.Others:						
2 · Mechanical Specification :						
1. PCB Size :	□ Pass	□ NG ,				
2.Frame Size :	□ Pass	□ NG ,				
3.Materal of Frame:	□ Pass	□ NG ,				
4.Connector Position:	□ Pass	□ NG ,				
5.Fix Hole Position:	□ Pass	□ NG ,				
6.Backlight Position:	□ Pass	□ NG ,				
7. Thickness of PCB:	□ Pass	□ NG ,				
8. Height of Frame to PCB:	□ Pass	□ NG ,				
9.Height of Module:	□ Pass	□ NG ,				
10.Others:	□ Pass	□ NG ,				
3 · Relative Hole Size :						
1.Pitch of Connector:	□ Pass	□ NG ,				
2.Hole size of Connector:	□ Pass	□ NG ,				
3.Mounting Hole size :	□ Pass	□ NG ,				
4.Mounting Hole Type:	□ Pass	□ NG ,				
5.Others:	□ Pass	□ NG ,				
4 · Backlight Specification :						
1.B/L Type:	□ Pass	□ NG ,				
2.B/L Color:	□ Pass	□ NG ,				
3.B/L Driving Voltage (Referen	ce for LED Ty	/pe):□ Pass □ NG ,				
4.B/L Driving Current:	□ Pass	□ NG ,				
5.Brightness of B/L:	□ Pass	□ NG ,				
6.B/L Solder Method:	□ Pass	□ NG ,				
7.Others:	□ Pass	□ NG ,				

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Module Number :					
5 · Electronic Characteristics of Module :					
1.Input Voltage:	□ Pass	□ NG ,			
2.Supply Current:	□ Pass	□ NG ,			
3.Driving Voltage for LCD:	□ Pass	□ NG ,			
4.Contrast for LCD:	□ Pass	□ NG ,			
5.B/L Driving Method:	□ Pass	□ NG ,			
6.Negative Voltage Output:	□ Pass	□ NG ,			
7.Interface Function:	□ Pass	□ NG ,			
8.LCD Uniformity:	□ Pass	□ NG ,			
9.ESD test:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
Sales signature :					
Customer Signature :		Date: / /			